

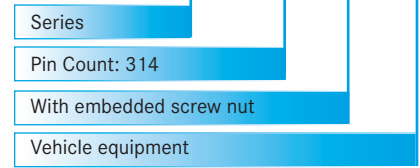
SPECIFICATIONS

Insulation Resistance:	250MΩ at 500V DC
Withstanding Voltage:	500V AC for 1 minute
Contact Resistance:	100mΩ max.
Current Rating:	0.7A
Voltage Rating:	50V DC
Operating Temp. Range:	-40°C to +105°C
Mating Cycles:	30 times

HIGH SPEED

PART NUMBER

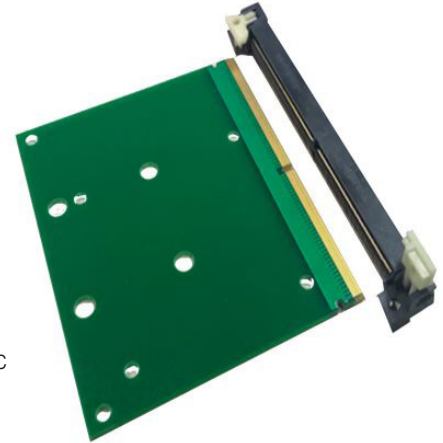
CNU113 - 314 - 2201 - VE



MATERIALS AND FINISH

Insulator:	LPC Heat resistance plastic
Contacts:	Copper Alloy
Contact Plating:	Contact Area - Selective Au Flash, 0,3μ" AU Solder Area - Au Flash Underplate - Ni
SMT Tabs:	Brass
SMT Plating:	Ni, Solder Tails Tin

AUTOMOTIVE COMPLIANT



FEATURES

- 314 pin automotive grade MXM3.1 connector
- High-speed data transmission 12 Gbps
- Clamshell latch + screw lock designs for secured module connection
- Compatible mechanical interface with MXM3.1 mobile spec and can be appropriated for SMARC
- Ideal for automotive infotainment and industrial embedded systems
- Excellent signal integrity performance, overshooting by far the MXM3.1 spec
- 90°, 0.5 mm pitch, mating height 5mm
- Automotive compliant

OUTLINE DIMENSIONS

